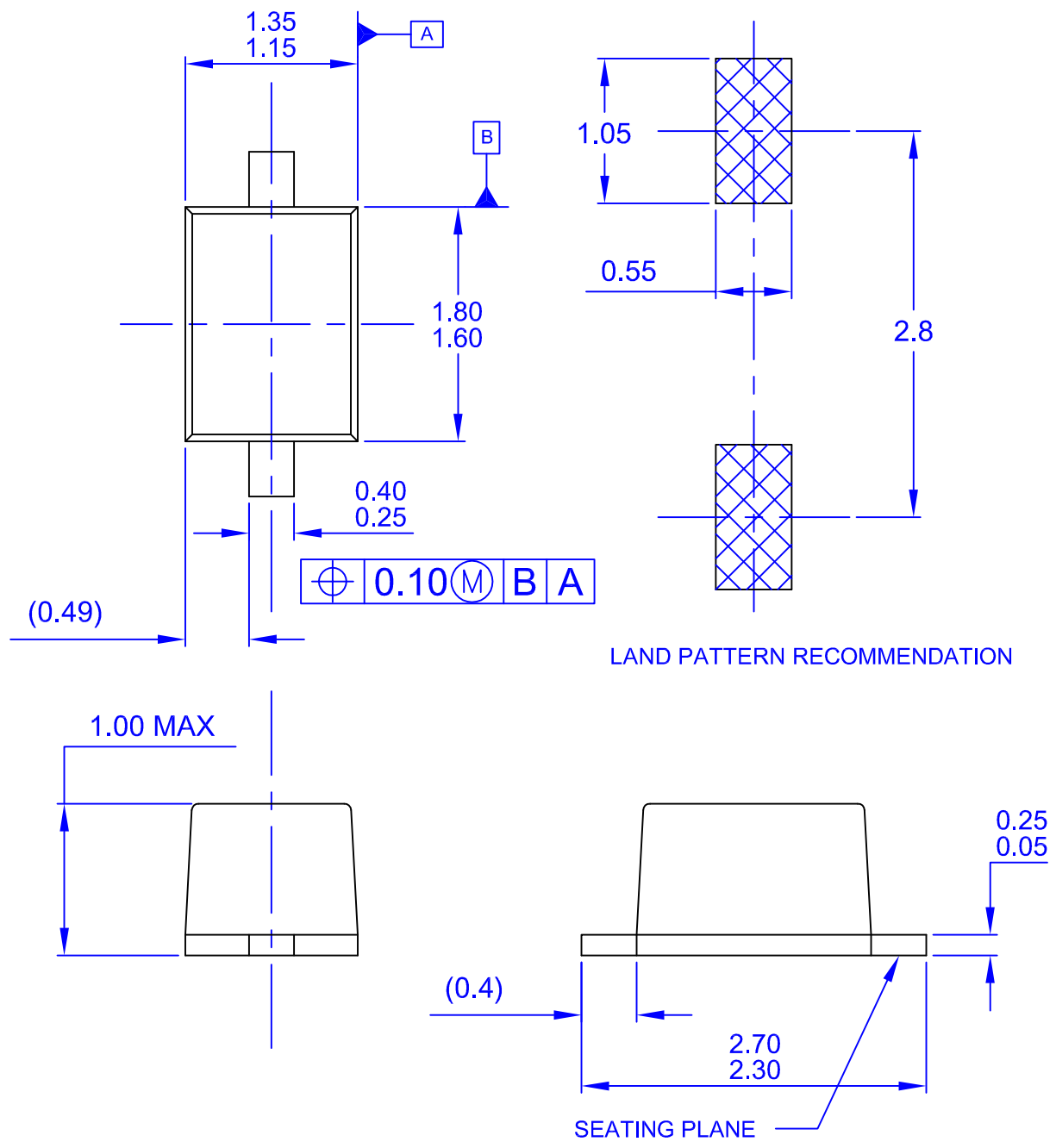


THIS DRAWING IS THE PROPERTY OF FAIRCHILD SEMICONDUCTOR CORPORATION. NO USE THEREOF SHALL BE MADE OTHER THAN AS A REFERENCE FOR PROPOSALS AS SUBMITTED TO FAIRCHILD SEMICONDUCTOR CORPORATION FOR JOBS TO BE EXECUTED IN CONFORMITY WITH SUCH PROPOSALS UNLESS THE CONSENT OF SAID FAIRCHILD SEMICONDUCTOR CORPORATION HAS PREVIOUSLY BEEN OBTAINED. NO PART OF THIS DRAWING SHALL BE COPIED OR DUPLICATED OR ITS CONTENTS DISCLOSED. THE INFORMATION CONTAINED ON THIS DRAWING IS CONFIDENTIAL AND PROPRIETARY.

REVISIONS			
LTR	DESCRIPTION	DATE	BY/SITE
1	RELEASE TO DOCUMENT CONTROL	15FEB2007	
2	CHANGE PACKAGE WIDTH FROM 1.45-1.15 TO 1.35-1.15; LAND PATTERN RECOMMENDATION CONFORMS TO SOD2514x110M	08JAN2008	S.D. LEE/SUZHOU



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) PACKAGE REFERENCE: THIS PACKAGE OUTLINE CONFORMS TO JEITA SC90, STANDARD EXCEPT FOR THE OVERALL PACKAGE HEIGHT.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DRAWING CONFORMS TO ASME Y14.5M - 1994 .
 - D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - E) LANDPATTERN RECOMMENDATION IS BASED ON IPC7351A STANDARD SOD2514X110M.
 - F) DRAWING NUMBER AND REVISION:MKT-SOD 323F2rev2

APPROVALS	DATE			
DRAWN: CHRISTOPHER DAI	08JAN2008			
CHECKED: BOBOY MALDO				
APPROVED: SILNORE SABANDO				
S.D. LEE		2LD, SOD323F, JEITA SC90, 1.0 MM, TALL		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	1:1	A3	MKT-SOD323F2	2
INCH END	FORMERLY: N/A	SHEET : 1 OF 1		